



EU-projects



Besi

Development of new products and technologies

Besi is a leading supplier of semiconductor assembly equipment for the global semiconductor and electronics industries. We develop leading edge assembly processes and equipment for leadframe, substrate and wafer level packaging applications in a wide range of end-user markets including electronics, mobile internet, computer, automotive, industrial, LED and solar energy.

Besi always researches new innovative technologies. Therefore we continuously participate in several EU projects to develop new products and new production technologies. This flyer shows some of the projects Besi has participated in. Feel free to contact us for more information. We can help to develop your future.

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Lab4MEMS-II – Micro-Optical MEMS, micro-mirrors and pico-projectors (ENIAC 2014 – 2017): Development of a Pilot Line for innovative technologies on advanced Micro-Opto-Electro-Mechanical Systems (MOEMS). Leader STMicroelectronics - www.lab4mems2.ite.waw.pl



PowerBASE (ECSEL 2015 – 2018): Enhanced substrates and GaN pilot lines enabling compact power applications. Leader: Infineon - www.powerbase-project.eu



EAST – smart Everything everywhere Access to content through Small cells Technologies (CATRENE 2015-2018): Development of enablers and facilitators for 5G Small cells mobile networks up to 6 GHz. Leader: NXP-NL



ENLIGHT

Enlight – Energy Efficient and Intelligent Lighting Systems (ENIAC 2011 – 2014): Exploitation of the full potential of Solid State Lighting through breakthrough innovations in non-conventional, energy efficient, and intelligent lighting systems, far beyond retrofit applications. Leader: Philips - www.enlight-project.eu



ATHENIS3D – Automotive Tested High Voltage and Embedded Non-Volatile Integrated System on Chip platform employing 3D Integration (FP7 2013 – 2016): Development of a new technology platform for automotive electronics with the use of 3D integration, through silicon vias (TSVs) and wafer level packaging (WLP). Leader: AMS - www.athenis3d.eu



R2Power – Preparing R2 extension to 300mm for BCD Smart Power and Power Discrete (ECSEL 2015 – 2018): Development of BCD (Bipolar-CMOS-DMOS) smart power and power discretes by technological innovation fitting smart power applications focused on high quality and mass production costs optimization. Leader: ST - <http://r2power300.eu>



InForMed – An integrated pilot line for micro-fabricated medical devices (ECSEL 2015 – 2018): Establishment of a pilot line for micro-fabricated of medical devices, bringing together key industrial and academic players in a manufacturing ecosystem. Leader: Philips <http://informed-project.eu>